



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-11-17
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC10H065G-TR	7SD2*3D091T6	A	3068	2017-11-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-9.15-4.5	2	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.09	Die / Leadframe	67
Lead	2.43	Soft solder	1764
Antimony trioxide	7.09	Mold compound	5138

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	7SD2*3D091T6					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.243	mg	supplier	die	Silicium carbide	409-21-2		4.142	mg	976196	3001
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	5656	17
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	942	3
				supplier	metallization	Silver (Ag)	7440-22-4		0.041	mg	9663	30
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	236	1
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	236	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	943	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	3771	12
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.010	mg	2357	7
Leadframe	Copper & its alloys	778.631	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.536	mg	998594	563432
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	460	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	840	474
				supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	98	56
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
Soft solder	Solder	2.549	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.434	mg	954884	1764
				supplier	solder	Silver (Ag)	7440-22-4		0.064	mg	25108	46
				supplier	solder	Tin (Sn)	7440-31-5		0.051	mg	20008	37
Bonding wires	Other inorganic materials	1.447	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.447	mg	1000000	1049
Encapsulation	Other Organic Materials	590.641	mg	supplier	mold compound	Silica, vitreous	60676-86-0		476.056	mg	805999	344968
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		41.345	mg	70000	29960
				supplier	mold compound	Phenol resin	9003-35-4		23.626	mg	40001	17120
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		35.438	mg	59999	25680
				supplier	mold compound	Antimony Trioxide	1309-64-4		7.088	mg	12001	5136
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		4.135	mg	7000	2996
				supplier	mold compound	Carbon black	1333-86-4		2.953	mg	5000	2140
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804